

- 15W Output Power ⁽¹⁾
- Input Voltage Range:
36V to 75V
- 1500 VDC Isolation
- Low-Profile
- Current Limit
- Short-Circuit Protection
- Over-Temperature Shutdown
- UL1950 recognized
- CSA 22.2 950 certified
- Meets EN60950

The PT4100—48V series of dc/dc converters provide up to 18 Watts/in³ of isolated power in a single low-profile module. Designed to operate from a standard 48V telecom bus, these modules employ switching frequencies of up to 850kHz, planar magnetics, and surface-mount construction. They are designed for Telecom, Industrial, Computer, Medical, and other distributed power applications that require input-to-output isolation.

Specifications

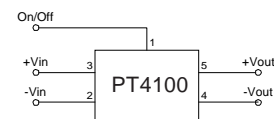
Characteristics (T _a =25°C unless noted)	Symbols	Conditions	PT4100—48V SERIES			Units
			Min	Typ	Max	
Output Current	I _o	Over V _{in} range V _o = 3.3V V _o = 5V V _o = 12V V _o = 15V	0 0 0 0	— — — —	4.0 ⁽¹⁾ 3.0 1.25 1.0	A
On/Off Standby Current	I _{in standby}	V _{in} = 48V, Pin 1 = -V _{in}	—	7	10	mA
Short Circuit Current	I _{sc}	V _{in} = 48V V _o ≤ 5.2V V _o = 12V V _o = 15V	— — — —	5.5 3.5 2.0	— — —	A
Inrush Current	I _{ir} t _{ir}	V _{in} = 48V @ max I _o On start-up	— —	0.6 1.0	1.0 5.0	A mSec
Input Voltage Range	V _{in}	I _o = 0.1 to max I _o	36.0	48.0	75.0	V
Output Voltage Tolerance	ΔV _o	Over V _{in} Range T _A = -40°C to +85°C	—	±1.0	±2.0	% V _o
Line Regulation	Reg _{line}	Over V _{in} range @ max I _o	—	±0.2	±1.0	% V _o
Load Regulation	Reg _{load}	10% to 100% of I _o max	—	±0.4	±1.0	% V _o
V _o Ripple/Noise	V _n	V _{in} =48V, I _o =4.0A, V _o =3.3V V _{in} =48V, I _o =3.0A, V _o =5V V _{in} =48V, I _o =1.25A, V _o =12V V _{in} =48V, I _o =1.0A, V _o =15V	— — — —	70 75 120 100	90 100 150 200	mV _{pp}
Transient Response	t _{tr}	50% load change V _o over/undershoot	— —	100 3.0	200 5.0	μSec % V _o
Efficiency	η	V _{in} =48V, I _o =4.0A, V _o = 3.3V V _{in} =48V, I _o =3.0A, V _o = 5V V _{in} =48V, I _o =1.25A, V _o =12V V _{in} =48V, I _o =1A, V _o =15V	— — — —	75 80 81 82	— — — —	%
Switching Frequency	f _o	Over V _{in} and I _o , V _o ≤ 5.2V V _o = 12V/15V	800 600	850 650	900 700	kHz
Recommended Operating Temperature Range	T _a	V _{in} = 48V @ max I _o Free air convection, (40-60LFM) PT4110 with 200 LFM airflow	-40 0	— —	+85 ⁽²⁾ +70 ⁽¹⁾	°C
Thermal Resistance	θ _{ja}	Free Air Convection, (40-60LFM)	—	14	—	°C/W
Case Temperature	T _c	@ Thermal shutdown	—	—	100	°C
Storage Temperature	T _s	—	-40	—	110	°C
Mechanical Shock	—	Per Mil-STD-202F, Method 213B, 6mS, Half-sine, mounted to a PCB	—	50	—	G's
Mechanical Vibration	—	Per Mil-STD-202F, Method 204D, 10-500Hz, Soldered in a PCB	—	10	—	G's
Weight	—	—	—	28	—	grams
Isolation Capacitance	—	—	1500	—	—	V
Resistance	—	—	10	1100	—	pF MΩ
Flammability	—	Materials meet UL 94V-0				
Remote On/Off	On ⁽³⁾ Off	Referenced to -V _{in}	2.5 0		7.0 0.8	V

Notes: (1) The PT4110 is limited to 13.2W output over the temperature range of 0–70°C with 200LFM airflow.

(2) See thermal derating curves

(3) If pin 2 is left open, the converter will operate when input power is applied

Standard Application



Pin-Out Information

Pin	Function
1	Remote ON/OFF
2	-V _{in}
3	+V _{in}
4	-V _{out}
5	+V _{out}
6	Do not connect

Ordering Information

Through-Hole

PT4101A = 5 Volts

PT4102A = 12 Volts

PT4103A = 15 Volts

(1) PT4110A = 3.3 Volts

PT4117A = 5.2 Volts

Surface Mount

PT4101C = 5 Volts

PT4102C = 12 Volts

PT4103C = 15 Volts

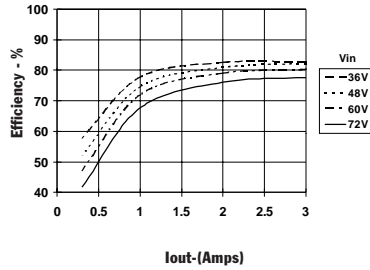
(1) PT4110C = 3.3 Volts

PT4117C = 5.2 Volts

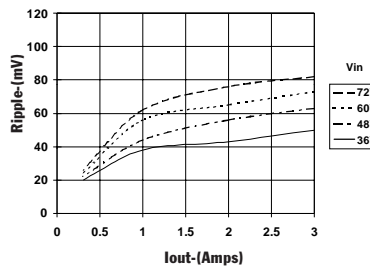
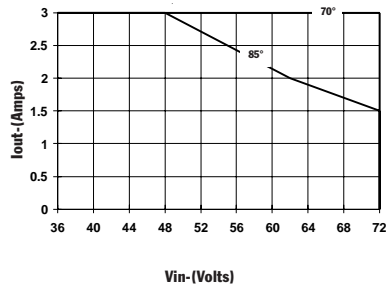
(For dimensions and PC board layout, see Package Style 710.)

PT4101, 5.0 VDC (See Note A.)

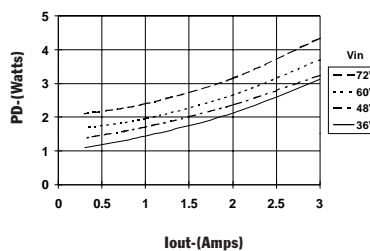
Efficiency vs Output Current



Ripple vs Output Current

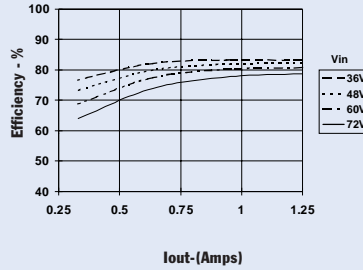
Thermal Derating (T_a) (See Note B.)

Power Dissipation vs Output Current

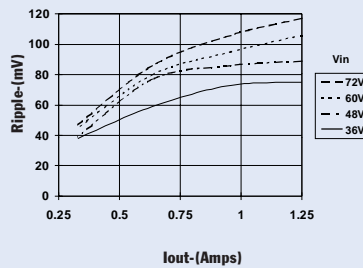
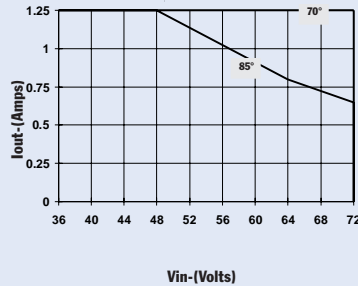


PT4102, 12.0 VDC (See Note A.)

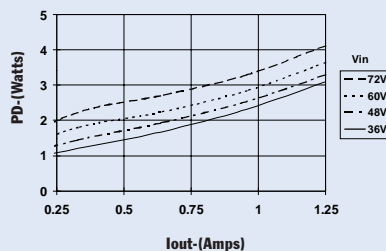
Efficiency vs Output Current



Ripple vs Output Current

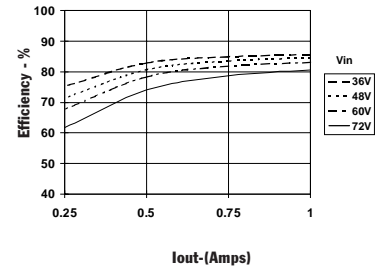
Thermal Derating (T_a) (See Note B.)

Power Dissipation vs Output Current

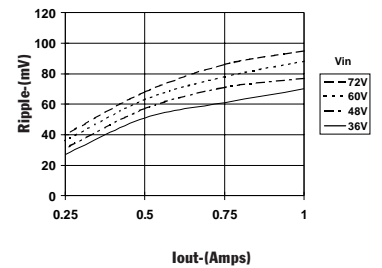
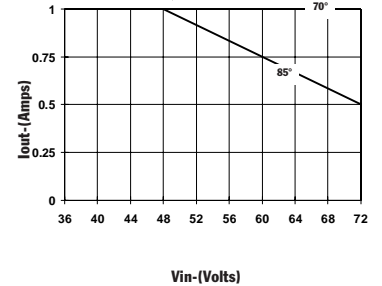


PT4103, 15.0 VDC (See Note A.)

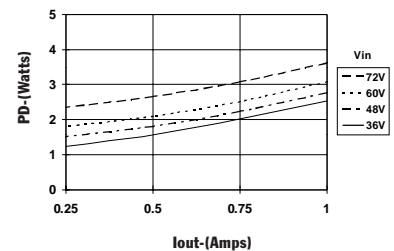
Efficiency vs Output Current



Ripple vs Output Current

Thermal Derating (T_a) (See Note B.)

Power Dissipation vs Output Current



Note A: All data listed in the above graphs, except for derating data, has been developed from actual products tested at 25°C. This data is considered typical data for the DC-DC Converter.
 Note B: Thermal derating graphs are developed in free air convection cooling of 40-60 LFM.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PT4101C	OBSOLETE	DIP MODULE	EGE	6		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com